

- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

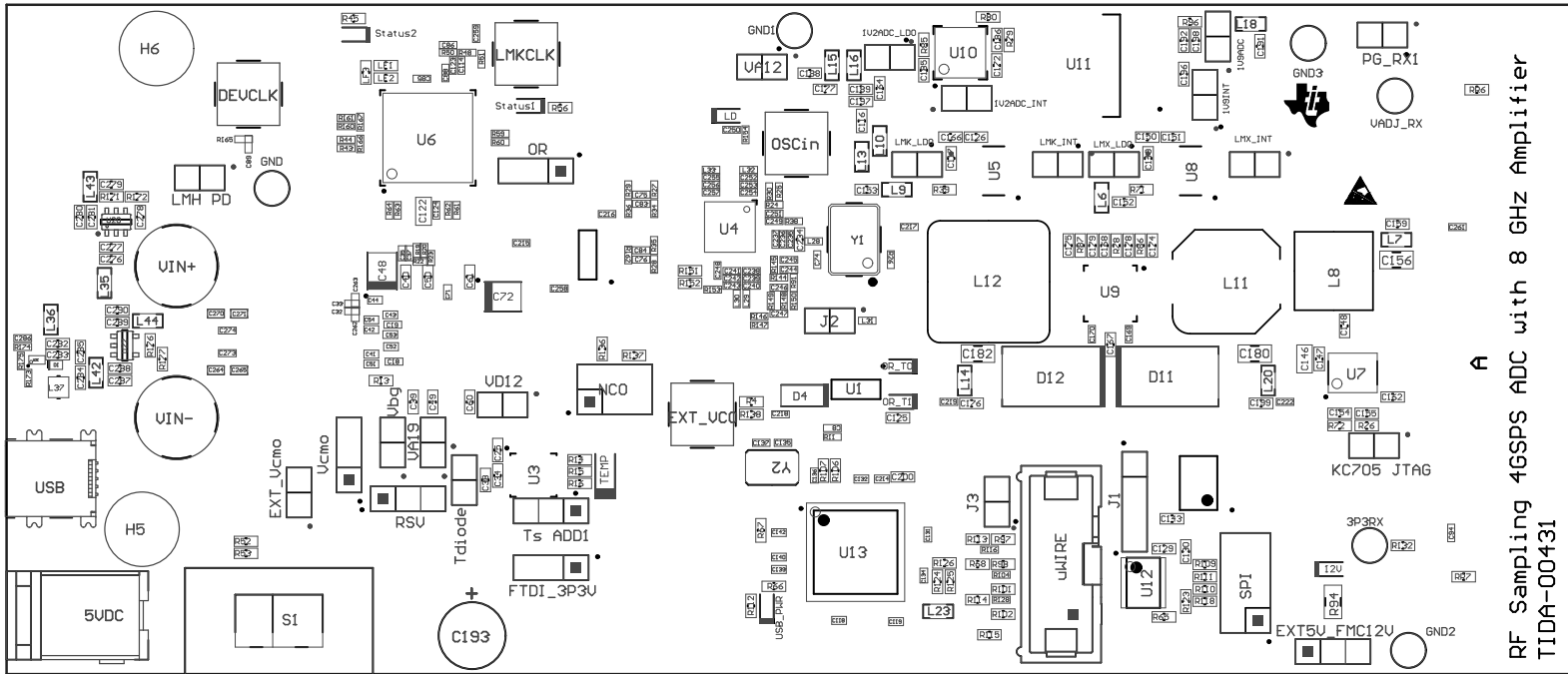
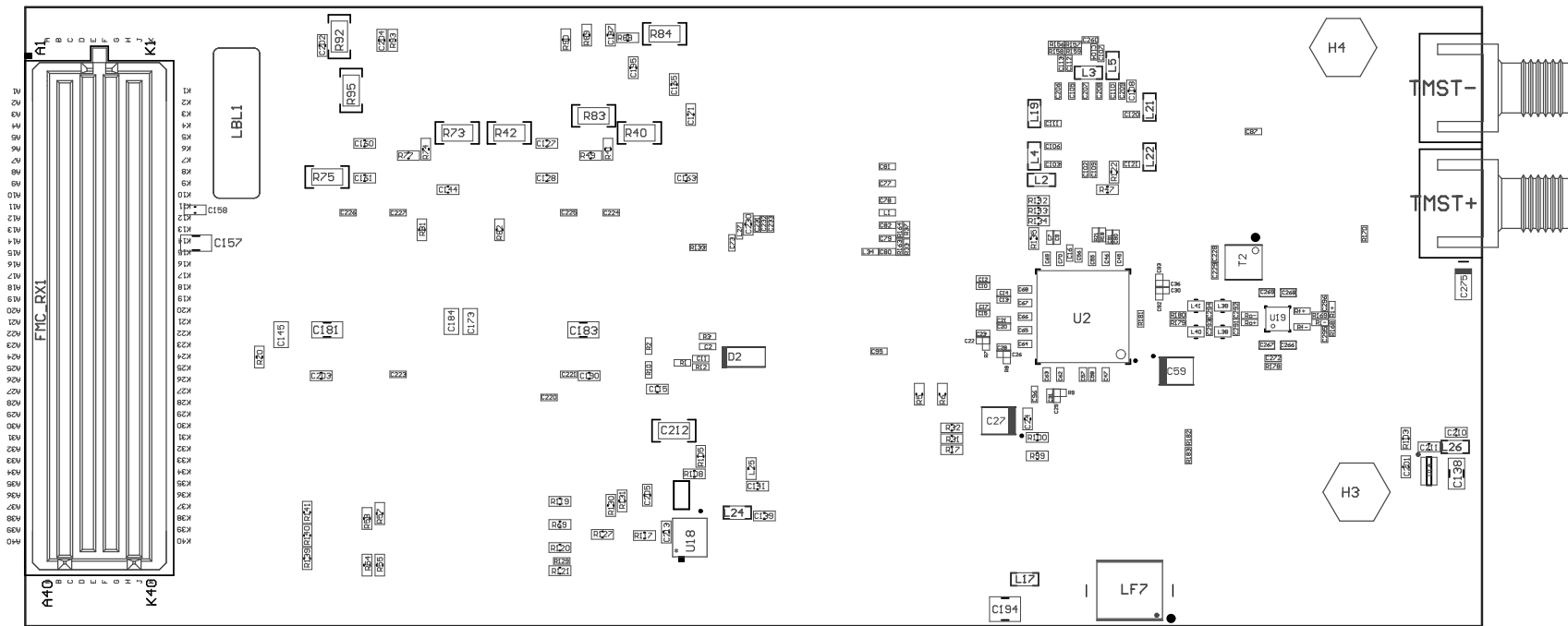


TABLE 1

Variant	Label text
001	TSW12J54EUM
002	TSW12J34EUM

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00431	REV: A	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 11/13/2015 10:31:18 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00431	REV: A	SUN REV: Not In VersionControl
	IGNORE ->		µrev0 Bottom Overlay
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/13/2015	10:31:19 AM	TEXAS INSTRUMENTS

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